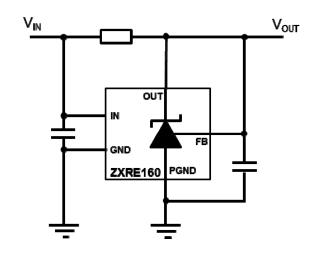


Typical Applications Circuit

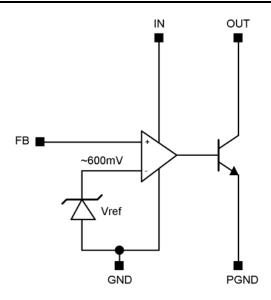


Pin Descriptions

Pin Name	Package Name Pin Number		Function	
riii Naille	SC70/ SOT353, TSOT25 X2-DFN1520-6			
PGND	1	1	Power Ground: Ground return for emitter of output transistor: Connect PGND and GND together.	
_	_	2	No connection	
OUT	5	3	Output: Connect a capacitor close to device between OUT and GND for closed loop stability. See the <i>Applications Information</i> section.	
FB	4	4	Feedback Input. Threshold voltage 600mV nominal.	
GND	2	5	Analog Ground: Ground return for reference and amplifier: Connect GND and PGND together.	
IN	3	6	Supply Input: Connect a 0.1µF ceramic capacitor close to the device from IN to GND.	
_	_	Flag	Floating or connect to GND	



Functional Block Diagram



The ZXRE160 differs from most other shunt regulators in that it has separate input and output pins and a low voltage reference. This enables it to regulate rails down to 600mV and makes the part ideal for isolated power supply applications that use opto-couplers in the feedback loop and where the open-collector output is required to operate down to voltages as low as 200mV.

The wide input voltage range of 2V to 18V and output voltage range of 0.2V to 18V enables the ZXRE160 to be powered from an auxiliary rail, while controlling a master rail which is above the

auxiliary rail voltage, or below the minimum V_{IN} voltage. This allows it to operate as a low-dropout voltage regulator for microprocessor/DSP/PLD cores.

As with other shunt regulators (and shunt references), the ZXRE160 compares its internal amplifier FB pin to a high accuracy internal reference; if FB is below the reference then OUT turns off, but if FB is above the reference then OUT sinks current – up to a maximum of 15mA.



Absolute Maximum Ratings (Voltages to GND, @TA = +25°C, unless otherwise specified.)

Symbol	Parameter	Rating	Unit
V _{IN}	IN Voltage relative to GND	20	V
Vout	OUT Voltage relative to GND	20	V
V_{FB}	FB Voltage relative to GND	20	V
P _{GND}	PGND Voltage relative to GND	-0.3 to +0.3	V
lout	OUT Pin Current	20	mA
TJ	Operating Junction Temperature	-40 to 150	°C
T _{ST}	Storage Temperature	55 to 150	°C

These are stress ratings only. Operation outside the absolute maximum ratings may cause device failure. Operation at the absolute maximum rating for extended periods may reduce device reliability.

Semiconductor devices are ESD sensitive and may be damaged by exposure to ESD events. Suitable ESD precautions should be taken when handling and transporting these devices.

Package Thermal Data

Package	θ _{JA}	P _{DIS} T _A = 25°C, T _J = 150°C
SC70/SOT353	400°C/W	310mW
TSOT25	250°C/W	500mW
X2-DFN1520-6	TBD	TBD

Recommended Operating Conditions (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Min	Max	Units
V _{IN}	IN Voltage Range (0 to +125°C)	2	18	
V _{IN} IN Voltage Range (-40°C to 0°C)		2.2	18	V
Vout	OUT Voltage Range	0.2	18	
I _{OUT}	OUT Pin Current	0.3	15	mA
T _A	Operating Ambient Temperature Range	-40	+125	°C



ZXRE160

Electrical Characteristics (@ $T_A = +25$ °C, $V_{DD} = 3V$, unless otherwise specified.)

 $T_A = +25$ °C, $V_{IN} = 3.3$ V, $V_{OUT} = V_{FB}$, $I_{OUT} = 5$ mA, unless otherwise specified.) (Note 4)

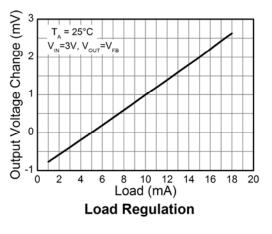
Symbol	Parameter		Conditions	<u> </u>	Min	Тур	Max	Units
				ZXRE160A	0.597	0.6	0.603	
				ZXRE160	0.594	0.6	0.606	
		T. 0°C to 105°C		ZXRE160A	0.595		0.605	1
		$T_A = 0$ °C to +85°C		ZXRE160	0.592		0.608	
V_{FB}	Feedback voltage	$T_A = -40^{\circ}\text{C to } +85^{\circ}$	C	ZXRE160A	0.594		0.606	V
		TA = -40 C to +65	C	ZXRE160	0.591		0.609	
		$T_A = -40^{\circ}\text{C to } +125^{\circ}$:•C	ZXRE160A	0.593		0.607	
		1A = -40 C to +125		ZXRE160	0.590		0.610	
FB_{LOAD}	Feedback pin load	I _{OUT} = 1 to 15mA				3.8	6	mV
I DLOAD	regulation	1001 = 1 to 13111A		$T_A = -40 \text{ to } +125^{\circ}\text{C}$			10	IIIV
FB _{LINE}	Feedback pin line	$V_{IN} = 2V$ to 18V				0.3	1	m\/
1 DLINE	regulation	$V_{IN} = 2.2V \text{ to } 18V$		$T_A = -40 \text{ to } +125^{\circ}\text{C}$			1.5	mV
	Output voltage	$V_{OUT} = 0.2V$ to 18V	,				1	,
FB _{OVR} regulation		I _{OUT} = 1mA (Ref. Figure 1)	$T_A = -40 \text{ to } +125^{\circ}\text{C}$			1.5	mV	
					-45		nA	
I_{FB}	FB input bias current	V _{IN} = 18V		$T_A = -40 \text{ to } +125^{\circ}\text{C}$	-200			0
				$V_{FB} = 0.7V$	-50			50
	V _{IN} = 2V to 18V	I _{OUT} = 0.3mA			0.35	0.7	mΛ	
		V _{IN} = 2.2V to 18V	1001 = 0.3111A	$T_A = -40 \text{ to } +125^{\circ}\text{C}$			1	mA
I_{IN}	Input current	V _{IN} = 2V to 18V	Jan - 10m A			0.48	1	
		$V_{IN} = 2.2V \text{ to } 18V$	I _{OUT} = 10mA	$T_A = -40 \text{ to } +125^{\circ}\text{C}$			1.5	mA
		V _{IN} = 18V, I _{OUT} = 0.	3mA	V _{FB} = 0.7V			3	
		V _{IN} = 18V,					0.1	
I _{OUT(LK)}	OUT leakage current	$V_{OUT} = 18V,$ $V_{FB} = 0V$	T _A = +125°C			1	μΑ	
_	Dynamic Output	I _{OUT} = 1 to 15mA				0.25	0.4	
Z_{OUT}	Impedance	f < 1kHz		$T_A = -40 \text{ to } +125^{\circ}\text{C}$			0.6	Ω
2022	Power supply rejection	F = 300kHz				45		j
PSRR	ratio	$V_{AC} = 0.3V_{PP}$				>45		dB
BW	Amplifier Unity Gain Frequency	Ref: Figure 2				600		kHz
G	Amplifier Transconductance					5000		mA/V

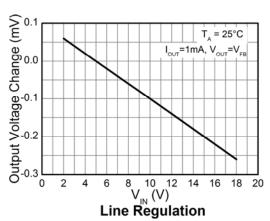
Note:

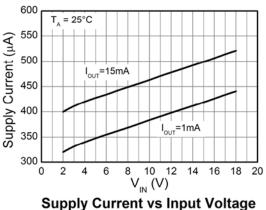
4. Production testing of the device is performed at +25°C. Functional operation of the device and parameters specified over the operating temperature range are guaranteed by design, characterization and process control.

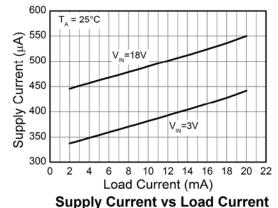


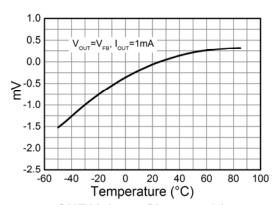
Typical Characteristics











-40
V_N=3.3V
V_{FB}=V_{OUT}
V_{FB}=V_{OUT}
-55
-60
-60 -40 -20 0 20 40 60 80 100
Temperature (°C)

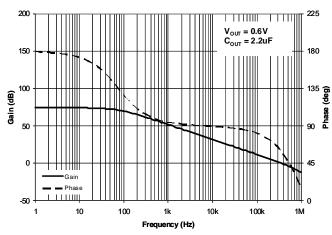
OUT Voltage Change with Temperature

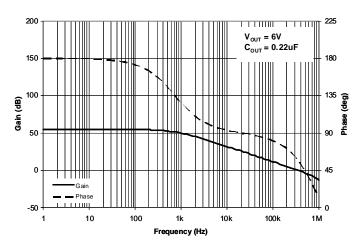
FB Bias Current vs Temperature



ZXRE160

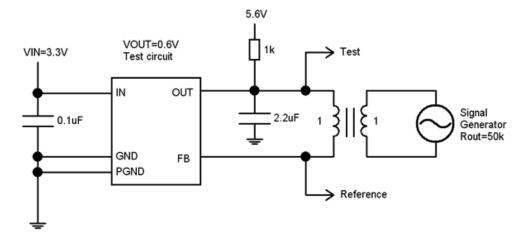
Typical Operating Characteristics





Gain and Phase vs Frequency, V_{OUT} =0.6V

Gain and Phase vs Frequency, $V_{OUT}=6V$



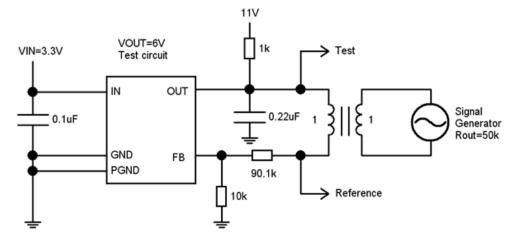


Figure 2. Test Circuits for Gain and Phase Plots



Application Information

The following show some typical application examples for the ZXRE160.

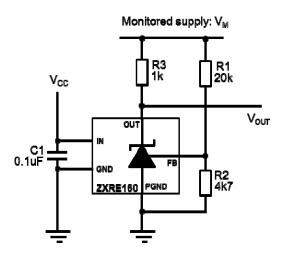


Figure 3 shows a typical configuration for the ZXRE160 in comparator mode.

Here the comparator switches low when:

$$V_{M} \geq \frac{V_{FB} \left(R_{1} + R_{2}\right)}{R_{2}}$$

Alternative values of R1, R2 may be used to provide different threshold voltages. R3 can also be adjusted to set the bias current for different values of $V_{\rm M}$. R2 should be kept as low as possible to minimize errors due to the bias current of the FB pin.

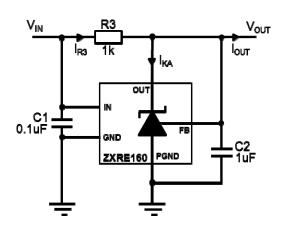
This circuit has no hysteresis, so a small capacitor of approx.4.7nF between FB and GND is recommended to provide cleaner transitions at the output.

Figure 3. 15V Supply Monitor

In shunt regulator mode it is necessary to include the compensation capacitor C2 to guarantee stability. C2 may range in value from $0.1\mu F$ to $10\mu F$ depending on the application. The minimum value of C2 can be determined from the following equation (resistor values are in $k\Omega$):

$$C2_{MIN} \ge \frac{R_2}{R_3(R_1 + R_2)} \mu F$$

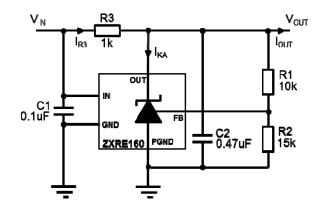
Both C1 and C2 should be as close to the ZXRE160 as possible and connected to it with the shortest possible track. In the case of Figure 10 and Figure 11, it means the opto-coupler will have to be carefully positioned to enable this.



$$V_{OUT} = V_{REF}$$

$$R3 = \frac{V_{IN} - V_{OUT}}{I_{R3}}$$

Figure 4. 0.6V Shunt Regulator



$$V_{OUT} = V_{REF} \left(1 + \frac{R1}{R2} \right)$$

$$R3 = \frac{V_{IN} - V_{OUT}}{I_{R3}}$$

Figure 5. 1.0V Shunt Regulator



Application Information (cont.)

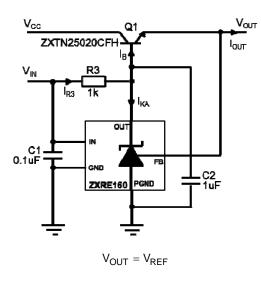


Figure 6. 0.6V Series LDO Regulator

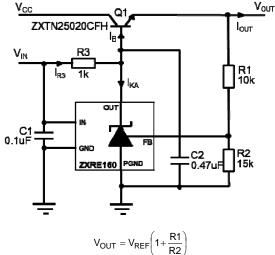


Figure 7. 1.0V Series LDO Regulator

Design guide:

Determine I_{OUT} and choose a suitable transistor taking power dissipation into consideration.

$$2. \quad \text{ Determine } I_B \text{ from } I_B = \frac{I_{OUT(max)}}{(h_{FE(min)} + 1)}$$

- Determine I_{R3} from $I_{R3} \ge I_B + I_{KA(min)}$. The design of the ZXRE160 effectively means there is no $I_{KA(min)}$ limitation as in conventional references. There is only an output leakage current which is a maximum of 1µA. Nevertheless, it is necessary to determine an I_{KA(min)} to ensure that the device operates within its linear range at all times. $I_{KA(min)} \ge 10\mu A$ should be adequate for this.
- Determine R3 from R3 = $\frac{V_{IN} (V_{OUT} + V_{BE})}{I_{R3}} \; . \label{eq:R3}$

Although unlikely to be a problem, ensure that $I_{R3} \le 15$ mA.



Application Information (cont.)

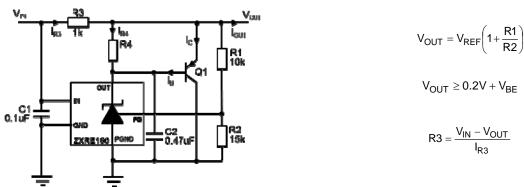
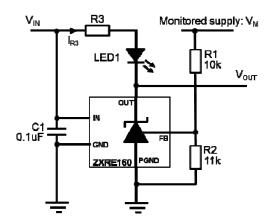


Figure 8. 1V Current-Boosted Shunt Regulator

Design guide

- 1. Determine I_{OUT} and choose a suitable transistor taking power dissipation into consideration.
- 2. Determine I_B from $I_B = \frac{I_{OUT(max)}}{(h_{FE(min)} + 1)}$
- 3. Determine I_{R3} from $I_{R3} = I_{OUT(max)}$
- 4. Determine R3 from R3 = $\frac{V_{IN} V_{OUT}}{I_{R3}}$
- 5. It is best to let the ZXRE160 supply as much current as it can before bringing Q1 into conduction. Not only does this minimize the strain on Q1, it also guarantees the most stable operation. Choose a nominal value between 10mA and <15mA for this current, I_{R4}.

Calculate R4 from R4 =
$$\frac{V_{BE}}{I_{R4}}$$



V_{OUT} goes low and LED is lit when monitored supply

$$V_{M} > V_{REF} \left(1 + \frac{R1}{R2} \right)$$

$$R3 = \frac{V_{IN} - (V_F + 0.2)}{I_{R3}}$$

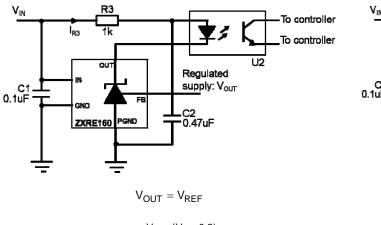
$$15mA \ge I_{R3} \le I_{F(MAX)}$$

V_F and I_F are forward voltage drop and current of LED1.

Figure 9. 1.15V Over-Voltage Indicator



Application Information (cont.)



$$R3 = \frac{V_{IN} - (V_F + 0.2)}{I_{R3}}$$

$$15mA \ge I_{R3} \le I_{F(MAX)}$$

V_{IN}

R3

To controller

$$V_{OUT} = V_{REF} \left(1 + \frac{R1}{R2} \right)$$

$$R3 = \frac{V_{IN} - (V_F + 0.2)}{I_{R3}}$$

$$15mA \ge I_{R3} \le I_{F(MAX)}$$

Figure 10. Opto-Isolated 0.6V Shunt Regulator

Figure 11. Opto-Isolated 1.0V Shunt Regulator

V_F and I_F are forward voltage drop and forward current respectively for the optocoupler LED

More applications information is available in the following publications which can be found on Diodes' web site.

AN58 - Designing with Diodes' References - Shunt Regulation

AN59 - Designing with Diodes' References - Series Regulation

AN60 - Designing with Diodes' References - Fixed Regulators and Opto-Isolation

AN61 - Designing with Diodes' References - Extending the operating voltage range

AN62 - Designing with Diodes' References - Other Applications

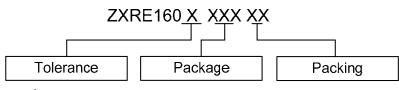
AN63 - Designing with Diodes' References - ZXRE060 Low Voltage Regulator

Pb



ZXRE160

Ordering Information



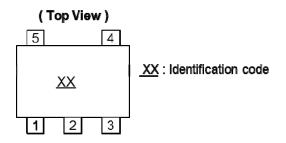
A: ±0.5% ET5: SOT25 -7: Tape & Reel None: ±1.0% H5: SOT353 TA: Tape & Reel

FT4: X2-DFN1520-6

Tol.	Part Number	Package	Identification Code	Reel Size	Tape Width	Quantity/Reel
0.5%	ZXRE160AET5TA	TSOT25	R8	7", 180mm	8mm	3000
	ZXRE160AH5TA	SC70/SOT353	R9	7", 180mm	8mm	3000
	ZXRE160AFT4-7	DFN1520H4-6	R8	7", 180mm	8mm	3000
	ZXRE160ET5TA	TSOT25	Z8	7", 180mm	8mm	3000
1%	ZXRE160H5TA	SC70/SOT353	Z9	7", 180mm	8mm	3000
	ZXRE160FT4-7	X2-DFN1520-6	Z8	7", 180mm	8mm	3000

Marking Information

1. TSOT25, SC70/SOT353



2. X2-DFN1520-6



XX: Identification code

<u>Y</u>:Year:0~9

<u>W</u>: Week : A~Z : 1~26 week; a~z: 27~52 week; z: represents 52 and 53

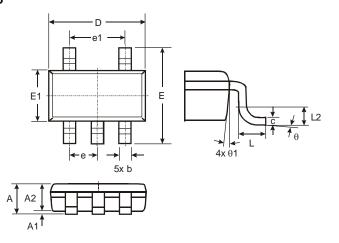
X: A~Z: Internal Code



ZXRE160

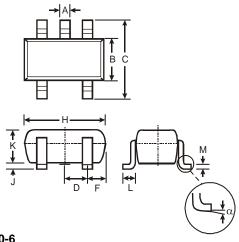
Package Outline Dimensions (All dimensions in mm.)

TSOT25



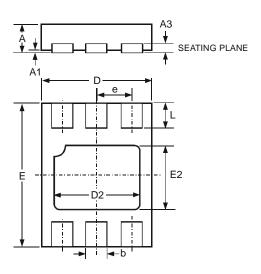
	TSOT25					
Dim	Min	Max	Тур			
Α	_	1.00	-			
A 1	0.01	0.10	1			
A2	0.84	0.90	1			
D	-	_	2.90			
Е	-	-	2.80			
E1	-	_	1.60			
b	0.30	0.45	_			
С	0.12	0.20	1			
е	-	_	0.95			
e1	-	_	1.90			
L	0.30	0.50				
L2	-	_	0.25			
θ	0°	8°	4°			
θ1	4°	12°	-			
AII D	imensi	ons in	mm			

SC70/SOT353



SOT353					
Dim	Min	Max			
Α	0.10	0.30			
В	1.15	1.35			
С	2.00	2.20			
D	0.65	Тур			
F	0.40	0.45			
Н	1.80	2.20			
J	0	0.10			
K	0.90	1.00			
L	0.25	0.40			
М	0.10	0.22			
α	0°	8°			
All Dimensions in mm					

X2-DFN1520-6

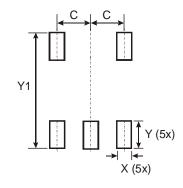


>	X2-DFN1520-6					
Dim	Min	Max	Тур			
Α	1	0.40	-			
A1	0	0.05	1			
А3	1	_	0.13			
b	0.20	0.30	1			
D	1.45	1.575	-			
D2	1.00	1.20	-			
е	-	_	0.50			
Е	1.95	2.075	1			
E2	0.70	0.90	-			
Ĺ	0.25	0.35	-			
All D	All Dimensions in mm					



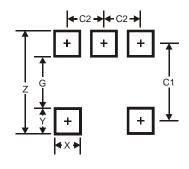
Suggested Pad Layout

TSOT25



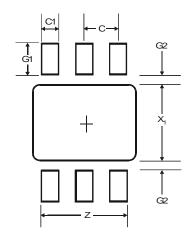
Dimensions	Value (in mm)
С	0.950
Х	0.700
Y	1.000
Y1	3.199

SC70/SOT353



Dimensions	Value (in mm)
Z	2.5
G	1.3
Х	0.42
Y	0.6
C1	1.9
C2	0.65

X2-DFN1520-6



Dimensions	Value (in mm)
Z	1.25
G1	0.45
G2	0.15
X1	1.10
С	0.50
C1	0.25



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